

#### DESCRIPTION

The SPN8205W is the Common-Drain Dual N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, notebook computer power management and other battery powered circuits where high-side switching.

#### **FEATURES**

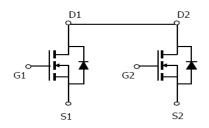
- 20V/5.0A, RDS(ON)=  $24m\Omega(a)V$ GS= 4.5V
- 20V/3.0A,RDS(ON)=  $34m\Omega$ @VGS= 2.5V
- ◆ Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ TSSOP 8P package design

#### APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

### PIN CONFIGURATION(TSSOP - 8P)





#### **PART MARKING**



## PIN DESCRIPTION

Pin	Symbol Description	
1	D1 / D2	Drain
2	S1	Source
3	S1	Source
4	G1	Gate
5	G2	Gate
6	S2	Source
7	S2	Source
8	D1 / D2	Drain

### **ORDERING INFORMATION**

Part Number	Package	Part Marking
SPN8205WTS8RGB	TSSOP- 8P	8205W

<sup>※</sup> SPN8205WTS8RGB: 13" Tape Reel; Pb − Free; Halogen - Free

# ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		VDSS	20	V
Gate –Source Voltage		VGSS	±8	V
Continuous Dusin Comment(Tr-150°C)	TA=25°C	In	5.0	А
Continuous Drain Current(T <sub>J</sub> =150°C)	Ta=70°C	ID ID	4.0	A
Pulsed Drain Current	Ідм	20	А	
Continuous Source Current(Diode Conduction)		Is	2.3	А
TA=2.		Dr	1.5	W
Power Dissipation	TA=70°C	PD	0.9	W
Operating Junction Temperature		TJ	-55/150	$^{\circ}$
Storage Temperature Range		Tstg	-55/150	$^{\circ}\mathbb{C}$
Thermal Resistance-Junction to Ambient		RθJA	80	°C/W



## **ELECTRICAL CHARACTERISTICS**

(Ta=25°C Unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20	-	-	٧
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	-	-	24	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =3A	-	-	34	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.25	-	1	٧
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =5A	-	18	-	S
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V	-	-	10	uA
I <sub>GSS</sub>	Gate-Source Leakage	V <sub>GS</sub> = <u>+</u> 8V, V <sub>DS</sub> =0V	-	-	<u>+</u> 100	nΑ
Qg	Total Gate Charge <sup>2</sup>	I <sub>D</sub> =5A	-	7.2	11.5	nC
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =16V	-	0.6	-	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	V <sub>GS</sub> =4.5V	-	3.4	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time <sup>2</sup>	V <sub>DS</sub> =10V	-	6.2	-	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =1A	-	10	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	$R_G=3.3\Omega,V_{GS}=5V$	-	15	-	ns
t <sub>f</sub>	Fall Time	$R_D=10\Omega$	-	5	-	ns
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	-	275	440	рF
Coss	Output Capacitance	V <sub>DS</sub> =20V	-	95	-	рF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	85	-	рF
R <sub>g</sub>	Gate Resistance	f=1.0MHz	-	2.2	-	Ω

# Source-Drain Diode

Symbol	ool Parameter Test Conditions		Min.	Тур.	Max.	Units		
$V_{SD}$	Forward On Voltage <sup>2</sup>	I <sub>S</sub> =0.7A, V <sub>GS</sub> =0V	-	-	1.2	V		
t <sub>rr</sub>	Reverse Recovery Time <sup>2</sup>	I <sub>S</sub> =2A, V <sub>GS</sub> =0V,	-	18.5	-	ns		
Q <sub>rr</sub>	Reverse Recovery Charge	dl/dt=100A/µs	-	9	-	nC		



### TYPICAL CHARACTERISTICS

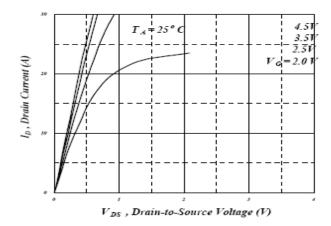


Fig 1. Typical Output Characteristics

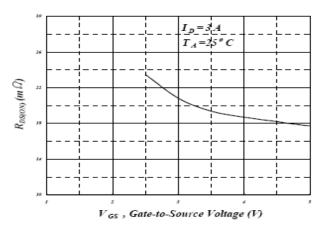


Fig 3. On-Resistance v.s. Gate Voltage

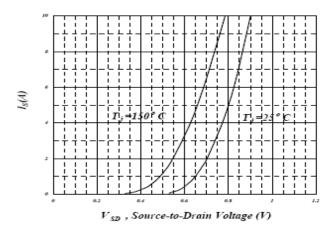


Fig 5. Forward Characteristic of Reverse Diode

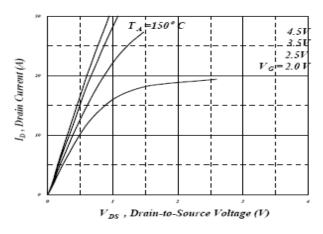


Fig 2. Typical Output Characteristics

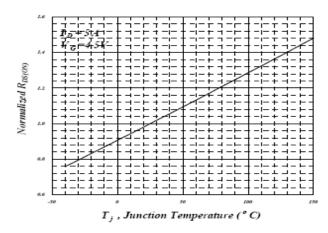


Fig 4. Normalized On-Resistance v.s. Junction Temperature

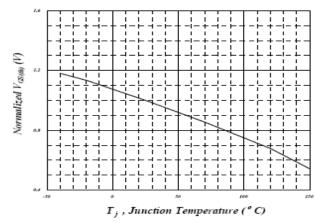


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



### TYPICAL CHARACTERISTICS

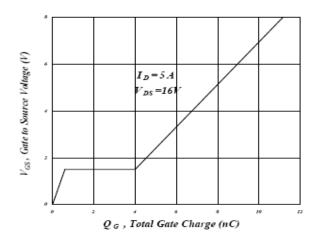


Fig 7. Gate Charge Characteristics

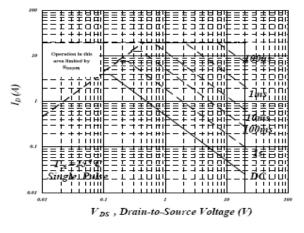


Fig 9. Maximum Safe Operating Area

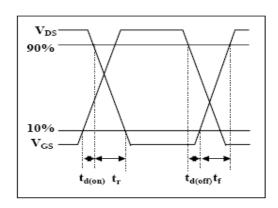


Fig 11. Switching Time Waveform

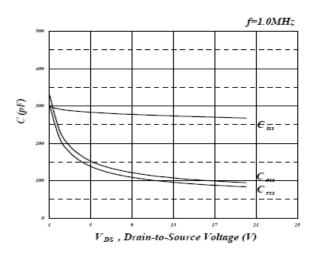


Fig 8. Typical Capacitance Characteristics

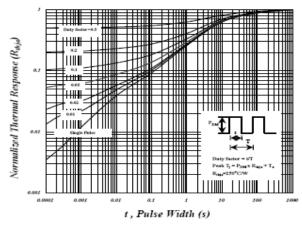


Fig 10. Effective Transient Thermal Impedance

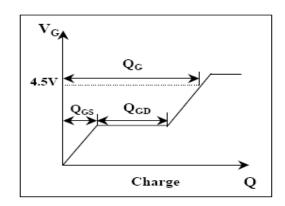
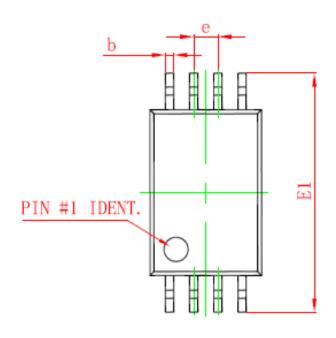
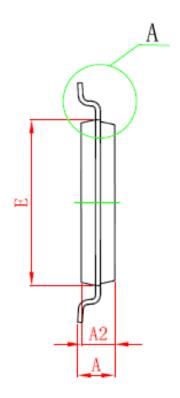


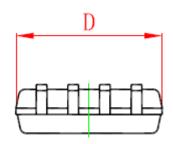
Fig 12. Gate Charge Waveform



# TSSOP- 8P PACKAGE OUTLINE







Symbol	Dimensions In Millimeters		Dimensions In Inches		
3 y 111 0 0 1	Min	Max	Min	Max	
D	2.900	3.100	0.114	0.122	
Е	4.300	4.500	0.169	0.177	
b	0.190	0.300	0.007	0.012	
С	0.090	0.200	0.004	0.008	
E1	6.250	6.550	0.246	0.258	
A		1.100		0.043	
A2	0.800	1.000	0.031	0.039	
A1	0.020	0.150	0.001	0.006	
e	0.65 (BSC)		0.026	(BSC)	
L	0.500	0.700	0.020	0.028	
Н	0. 25 (TYP)		0. 25 (TYP) 0. 01 (TYP)		(TYP)
θ	1°	7°	1 °	7°	



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